

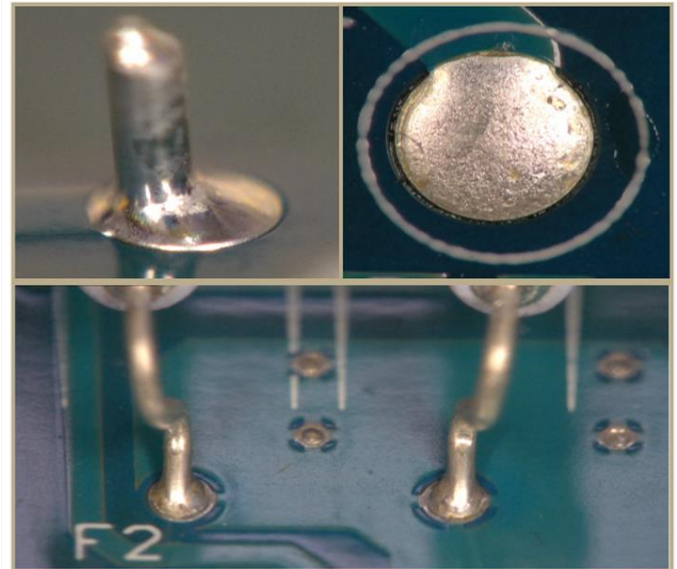
NC265 LIQUID FLUX

FEATURES

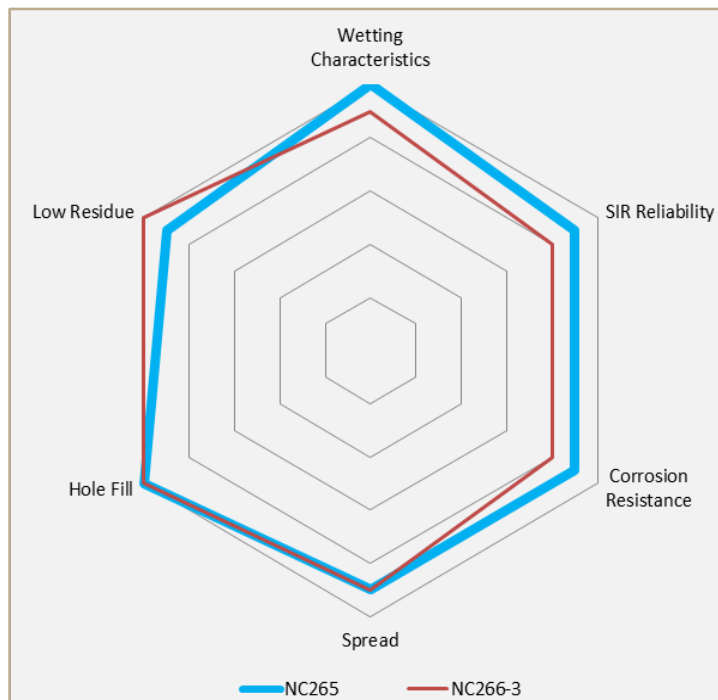
- Broad Process Window
- Fast Wetting for Lead-Free Alloys
- Halide-Free
- Low Post Process Residues
- REACH Compliant

DESCRIPTION

NC265 is an alcohol-based no-clean liquid flux formulated to offer a very wide process window for lead-free and tin-lead wave soldering operations. NC265 promotes faster wetting than previously formulated fluxes for all lead-free alloys including SN100C®. NC265 is compatible with a broad range of lead-free and tin-lead solder alloys. NC265 leaves low post-process residues and reduces preventative maintenance and cleaning on pallets fixtures and spray equipment. NC265 is designed to be a no-clean flux which can be cleaned if critical to the product application.



CHARACTERISTICS



HANDLING & STORAGE

Parameter	Time	Temperature
Sealed Shelf Life	1 year	Room Temperature

NC265 has a sealed shelf life of one (1) year when stored at room temperature. Do not store near fire or flame. Keep away from sunlight as it may degrade product. NC265 is shipped ready-to-use, no mixing necessary. Do not mix used and unused chemical in the same container. Reseal any opened containers. Storage conditions range from 4° - 40° C (40 - 100°F).

APPLICATION

NC265 is formulated for application via spray, brush, mist, or dip. NC265 is ready to use directly from its container, no thinning required. When spray fluxing, proper flux coverage and uniformity are imperative. A dry flux coating of 500-1500 micrograms per square inch is recommended as a starting point. When nitrogen sealed wave solder equipment is used, it is generally necessary to apply additional flux.

PROCESS GUIDELINES

Using thermocouples attached to the top of the PCB, the topside assembly temperature should be between 85-110°C (185-230°F). It is important that the flux be dry prior to entering the wave regardless of temperature or spattering will occur. Smoking may occur and is considered normal if it is not excessive. Recommended contact time with the wave is dependent on wave configuration, pot temperature, alloy type and thermal mass of the assembly with 4-7 seconds being typical. For processing assistance, please contact AIM Technical Support by visiting <http://www.aimsolder.com/technical-support-contacts>.

CLEANING

NC265 can be cleaned using a saponifier or chemical cleaners. Contact AIM for additional information. Deionized water is recommended for the final rinse.

SAFETY

Use with adequate ventilation and proper personal protective equipment. Refer to the accompanying Material Safety Data Sheet for any specific emergency information. Do not dispose of any hazardous materials in non-approved containers.

TEST DATA SUMMARY

Name	Test Method	Results	
IPC Flux Classification	J-STD-004	ORLO	
IPC Flux Classification	J-STD-004B 3.3.1	ORLO	
Name	Test Method	Results	Image
Copper Mirror	J-STD-004 3.4.1.1 IPC-TM-650 2.3.32	LOW	
Corrosion	J-STD-004 3.4.1.2 IPC-TM-650 2.6.15	PASS	
Qualitative Halides, Silver Chromate	J-STD-004 3.5.1.1 IPC-TM-650 2.3.33	PASS	
Qualitative Halides, Fluoride Spot	J-STD-004 3.5.1.2 IPC-TM-650 2.3.35.1	PASS	

Name	Test Method	Results	Image
Surface Insulation Resistance	J-STD-004 3.4.1.4 IPC-TM-650 2.6.3.3	PASS	
Flux Solids, Nonvolatile Determination	J-STD-004 3.4.2.1 IPC-TM-650 2.3.34	4.20% Typical	
Acid Value Determination	J-STD-004 3.4.2.2 IPC-TM-650 2.3.13	35.95 Typical	
Flux Specific Gravity Determination	J-STD-004 3.4.2.3 ASTM D-1298	0.80 Typical	
pH (1% solution /water)	ASTM D5464 ASTM G51	4.37 Typical	
Visual	J-STD-004 3.4.2.5	Colorless	
Wetting	J-STD-005A 3.9 IPC-TM-650 2.4.45	PASS	